

I Number	Hits	Search Text	DB	Time stamp
1	52835	((polymeric polyimide polymer poymide) near4 substrate	USPAT; US-PGPUE; EPO; JPO; DERWENT	2003/02/24 09:13
2	602	((polymeric polyimide polymer poymide) near4 substrate) and (trace near4 substrate)	USPAT; US-PGPUE; EPO; JPO; DERWENT	2003/02/24 09:14
3	169	((polymeric polyimide polymer poymide) near4 substrate; and (trace near4 substrate); and 257/56.cols.	USPAT; US-PGPUE; EPO; JPO; DERWENT	2003/02/24 09:27
4	82	((polymeric polyimide polymer poymide) near4 substrate; and (trace near4 substrate)) and (MCM (multi-chip near module) (multi near chip near module))	USPAT; US-PGPUE; EPO; JPO; DERWENT	2003/02/24 09:46
5	21442	Yoshimura.in.	USPAT; US-PGPUE; EPO; JPO; DERWENT	2003/02/24 09:46
6	1810	Yoshimura.in. and optical	USPAT; US-PGPUE; EPO; JPO; DERWENT	2003/02/24 09:47
7	40	(Yoshimura.in. and optical) and polymeric	USPAT; US-PGPUE; EPO; JPO; DERWENT	2003/02/24 09:47
-	36	((polymeric polyimide polymer poymide) same (routing route) same trace same (chip die)	USPAT; US-PGPUE; EPO; JPO; DERWENT	2003/02/13 10:46
-	426	"routing element"	USPAT; US-PGPUE; EPO; JPO; DERWENT	2003/02/13 10:51
-	20	("routing element" and (chip die)) and trace	USPAT; US-PGPUE; EPO; JPO; DERWENT	2003/02/13 10:52
-	117	"routing element" and (chip die)	USPAT; US-PGPUE; EPO; JPO; DERWENT	2003/02/13 10:56
-	97	("routing element" and (chip die)) not (("routing element" and (chip die)) and trace)	USPAT; US-PGPUE; EPO; JPO; DERWENT	2003/02/13 11:01
-	2879	257/523	USPAT; US-PGPUE; EPO; JPO; DERWENT	2003/02/13 11:01
-	1917	257/660	USPAT; US-PGPUE; EPO; JPO; DERWENT	2003/02/13 11:01
-	888	257/660	USPAT; US-PGPUE; EPO; JPO; DERWENT	2003/02/13 11:01
-	1719	317/377	USPAT; US-PGPUE; EPO; JPO; DERWENT	2003/02/13 11:01
-	1710	317/377	USPAT; US-PGPUE; EPO; JPO; DERWENT	2003/02/13 11:01

-	1949	257/784	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/02/13 11:12
-	2047	257/784	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/02/13 11:12
-	1587	257/691	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/02/13 11:12
-	9396	257/723 257/686 257/685 257/777 257/730 257/784 257/786 257/691	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/02/13 11:17
-	2829	(257/723 257/686 257/685 257/777 257/730 257/784 257/786 257/691) and (polymeric polyimide polyimide polymer)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/02/13 11:18
-	846	((257/723 257/686 257/685 257/777 257/730 257/784 257/786 257/691) and (polymeric polyimide polyimide polymer)); and trace	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/02/13 11:18
-	258	((257/723 257/686 257/685 257/777 257/730 257/784 257/786 257/691) and (polymeric polyimide polyimide polymer); and trace) and (route routing)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/02/13 11:19
-	115	((257/723 257/686 257/685 257/777 257/730 257/784 257/786 257/691) and (polymeric polyimide polyimide polymer)); and trace) and (route routing)) and (bond near pad)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/02/13 11:25
-	3	"6420789"	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/02/13 14:46
-	0	"6522016"	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/02/13 14:50
-	13	pershelle	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/02/13 14:52
-	0	pershelle	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/02/13 14:52
-	0	pershelle	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/02/13 14:52
-	416	"routing element"	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/02/13 15:14
-	14	"routing element" and substrate and trace	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/02/13 15:18
-	1151	substrate near trace and bond near pad	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/02/13 15:18
-	1151	substrate near trace and bond near pad and chip die semiconductor device	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/02/13 15:18

-	54949	"wiring board"	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/02/19 15:36
-	3165	"wiring board" and carrier	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/02/19 15:36
-	451	"wiring board" and carrier and trace rout\$3"	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/02/19 15:36
-	155	"wiring board" and carrier and trace rout\$3); and (bond near pad	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/02/19 15:36
-	9387	((multi near chip) multichip) near5 module	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/02/20 09:11
-	1636	multi near chip; multichip; near5 module and trace and (chip die (semiconductor near device))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/02/20 09:13
-	617	((((multi near chip) multichip) near5 module) and trace and (chip die (semiconductor near device))) and (bond near pad)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/02/20 10:54
-	422	((((multi near chip) multichip) near5 module) and trace and (chip die (semiconductor near device))) and (bond near pad)) and (polymeric polymer polyimide polyimide polym\$4 polyim\$4)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/02/20 10:56
-	404	(((((multi near chip) multichip) near5 module) and trace and (chip die (semiconductor near device))) and (bond near pad)) and (polymeric polymer polyimide polyimide polym\$4 polyim\$4)) and substrate	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/02/20 11:23
-	116	(((((multi near chip) multichip) near5 module) and trace and (chip die (semiconductor near device))) and (bond near pad)) and (polymeric polymer polyimide polyimide polym\$4 polyim\$4)) and substrate) and rout\$4	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/02/20 11:24